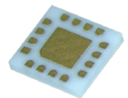
Comprehensive Packaging Solutions Portfolio

At Miller MMIC, we offer a diverse and high-performance variety of packaging solutions tailored to meet your precise engineering requirements. Supporting hundreds of products across our portfolio—spanning from low-power GaAs devices to high-power GaN technologies—we provide the optimal thermal, electrical, and environmental housing for your custom and standard applications.

Available Packaging Solutions

PACKAGE TYPE	FEATURES & APPLICATIONS
Ceramic QFN Package 	Available in standard **3mm, 4mm, and 5mm** configurations. These options feature a choice of either **hermetic or non-hermetic seals**, making them ideally suited for aerospace and space applications operating within airgas environments.
Plastic QFN Package	Offered with advanced **overmolding or air cavity packaging** options. This represents a highly cost-effective solution optimized for both low-power and high-power GaN devices.
Flanged Package	Engineered specifically to support **very high-power GaN Power Amplifiers (PAs)**, ensuring excellent thermal management and structural reliability under maximum operating demands.

Environmental Standards & Compliance

All Miller MMIC packaging solutions strictly adhere to international environmental directives and are fully **RoHS Compliant** and **REACH Compliant**.

Ready to Discuss Your Packaging Requirements?

Whatever your MMIC application calls for, we have the packaging technology to match. Contact the Miller MMIC technical sales team today to find the ideal solution for your next project.